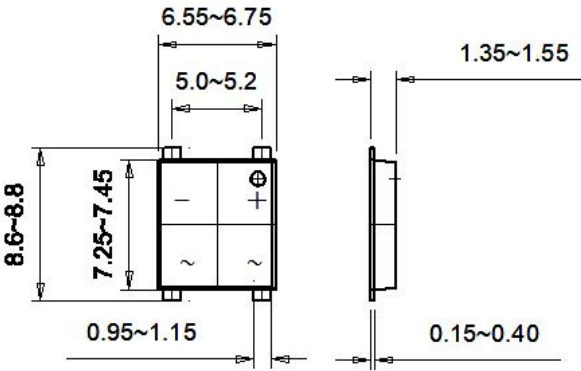




特征/Features	外形尺寸/Outline Dimensions
◆ GPP芯片 Glass passivated chip ◆ 低反向漏电流 Low Reverse Leakage Current ◆ 高耐浪涌电流能力 High surge current capability ◆ 接线端与壳体间绝缘耐压2500V Case to Terminal Isolation Voltage 2500V	Case: MSB Series Dimensions in millimeters  产品尺寸控制范围: $\pm 0.2\text{mm}$ ROHS COMPLIANT Pb-Free
机械参数/Machanical Data	
◆ 本体: 塑封 Case: plastic package ◆ 标识/极性: 本体标记 Marking / Polarity: Marked on Body ◆ 重量: 约克 Weight: About 0.24grams	

极限值/Maximum Ratings and Thermal Characteristics @ Ta = 25°C unless otherwise noted

符号 Symbol	特性 Characteristic	MSB3							单位 Unit
		0A	0B	0D	0G	0J	0K	0M	
V _{RRM}	最大反向重复峰值电压 Maximum Recurrent Peak Reverse Voltage	50	100	200	400	600	800	1000	V
I _F (AV)	平均整流输出电流 Average Forward Output Rectified Current@Ta=120°C	3							A
V _F	正向峰值电压 Forward Voltage Per Leg @I _{FM} =3.0A	1.05							V
I _{FSM}	正向浪涌电流 Peak Forward Surge Current 8.3ms Single Half Sine-wave superimposed on rated load	70							A
I _R	反向漏电流 Maximum DC reverse current at rated DC blocking voltage per leg	5 500							uA
i ² t	热容值 Rating for fusing (t<8.3ms)	20.3							A ² S
V _{isol}	绝缘耐压 Rms isolation voltage from case to leads	2500							V
C _J	典型结电容 Typical Junction Capacitance	23							pF
R _{θJC}	热阻 Maximum thermal resistance per leg	10							°C/W
T _j , T _{STG}	结温, 存储条件 Operating Junction and storage temperature range	-55~150							°C

Note:

- (1) Junction to case with heatsink
- (2) Recommended mounting position is to bolt down on heatsink with silicone thermal compound for maximum heat transfer with M3 screw .



◆ 特性曲线 (典型) Characteristics(Typical)

Fig 1-forwardCurrent derating Curve

图1正向电流降额曲线

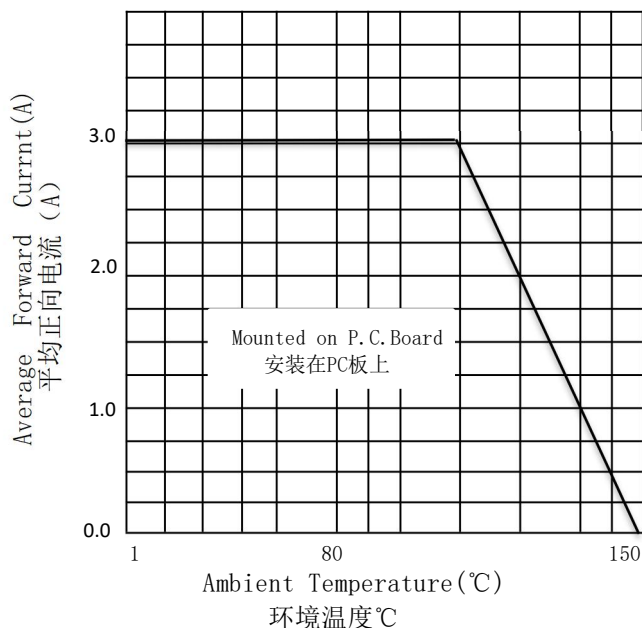


Fig.2-Maximum Non-Repetitive Surge Current

图2 最大不重复正向浪涌曲线

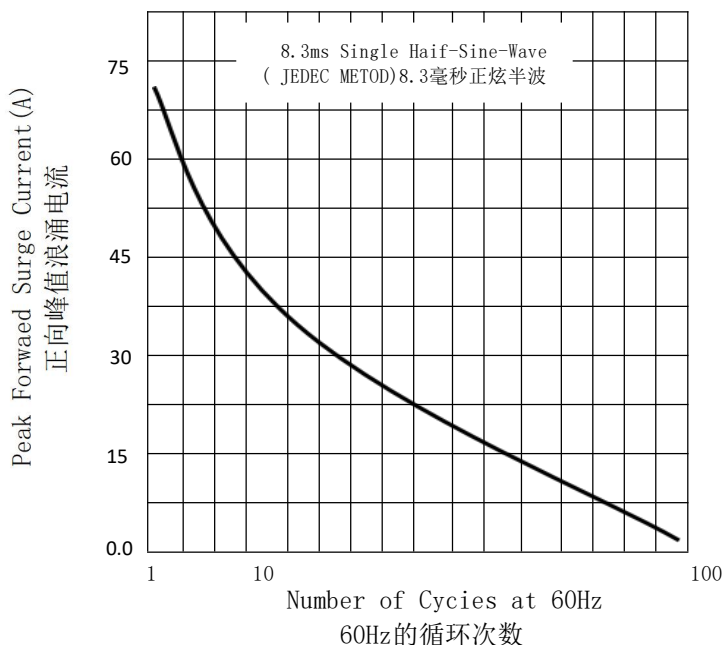


Fig.3-Typical Reverse Characteristics

图3. 典型的反向特性

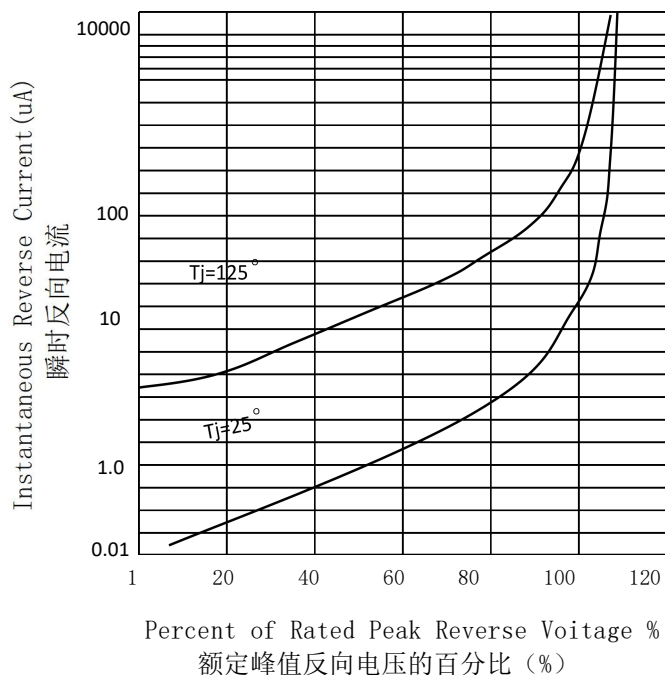
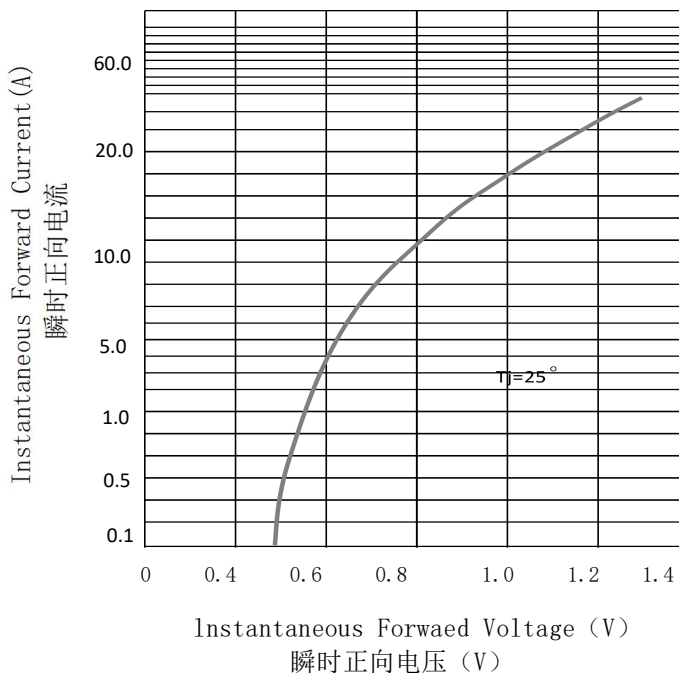


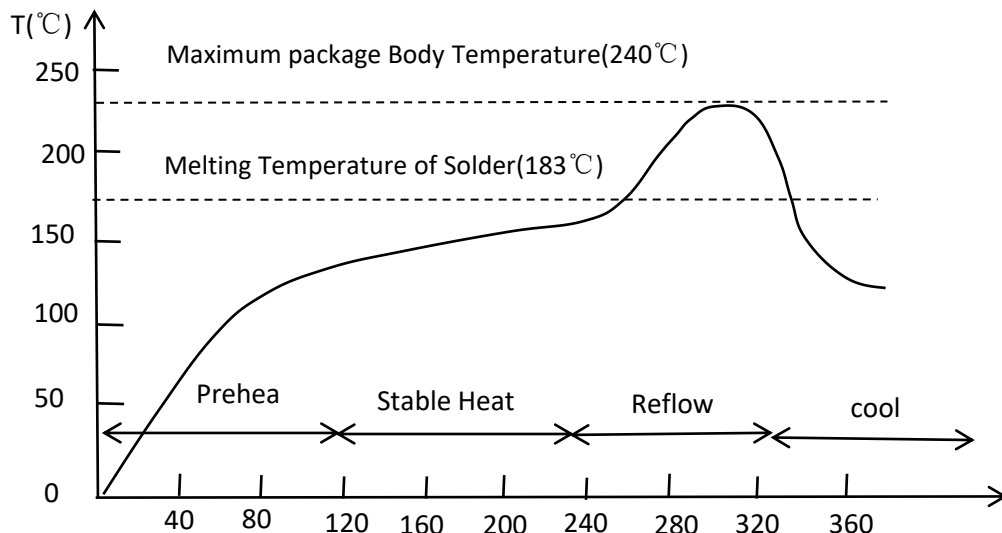
Fig.4-Typical Forward Characteristics

图4. 典型的正向特性





◆ 焊接温度 (Suggested Soldering Temperature profile



◆ 回流焊方法: 红外线、气相炉、热风炉、波峰焊

Recommended reflow methods: IR, vapor phase oven, hot air oven, wave solder.

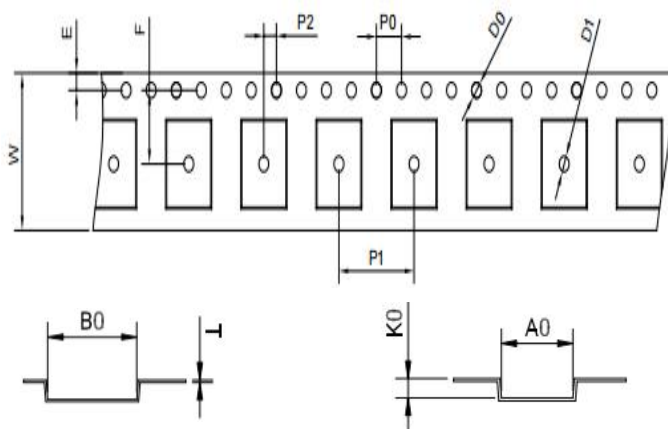
◆ 该装置可在 265° C 的最高温度下暴露 10 秒钟

The device can be exposed to a maximum temperature of 265 ° C for 10 seconds.

◆ 如果回流温度超过建议的温度, 则设备可能不符合性能要求。

If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

◆ 载带尺寸 Carrier Dimension(mm)



W	AO	B0	K0	E	F
16	7.05	8.8	1.65	1.75	7.50
D0	D1	P0	P1	P2	T
1.6	1.5	4.0	12.0	2.0	0.25

◆ 包装规格 Package Specifications

Package	Reel Siz	Reel DIA. (mm)	Q'TY/Reel (Kpcs)	Box Size (mm)	QTY/Box (Kpcs)	Carton Size (mm)	Q'TY/Carton (Kpcs)
MSB	13'	330	3	345	6	440*360*360	54